

Smart Sense High-Side Power Switch

Features

- Short circuit protection
- Current limitation
- Proportional load current sense
- CMOS compatible input
- Open drain diagnostic output
- Fast demagnetization of inductive loads
- Undervoltage and overvoltage shutdown with auto-restart and hysteresis
- Overload protection
- Thermal shutdown
- Overvoltage protection including load dump (with external GND-resistor)
- Reverse battery protection (with external GND-resistor)
- Loss of ground and loss of V_{bb} protection
- Electrostatic discharge (ESD) protection

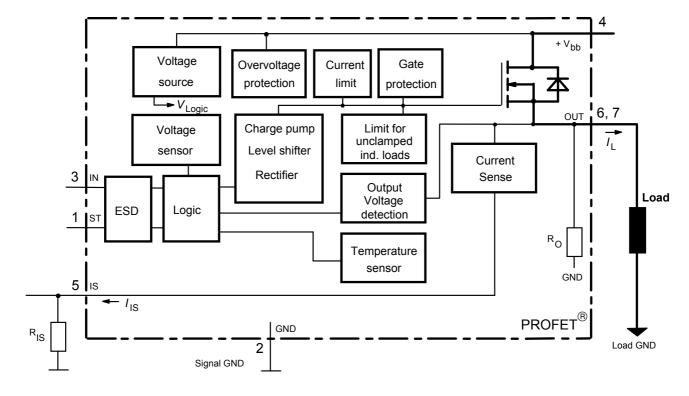
Application

- μC compatible power switch with diagnostic feedback for 12 V and 24 V DC grounded loads
- All types of resistive, inductive and capacitve loads
- Replaces electromechanical relays, fuses and discrete circuits

General Description

N channel vertical power FET with charge pump, ground referenced CMOS compatible input and diagnostic feedback, proportional sense of load current, monolithically integrated in Smart SIPMOS® technology. Providing embedded protective functions.

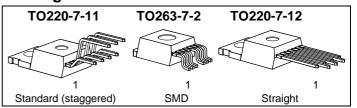
Block Diagram



Product Summary

$V_{bb(on)}$	5.0 34	٧	
R_{on}	30	$m\Omega$	
I _{L(ISO)}	12.6	Α	
I _{L(SCr)}	24	Α	
	R _{on} I _{L(ISO)}	R _{ON} 30 I _{L(ISO)} 12.6	R_{ON} 30 m Ω $I_{L(ISO)}$ 12.6 A

Package





Pin	Symbol	Function
1	ST	Diagnostic feedback: open drain, invers to input level
2	GND	Logic ground
3	IN	Input, activates the power switch in case of logical high signal
4	Vbb	Positive power supply voltage, the tab is shorted to this pin
5	IS	Sense current output, proportional to the load current, zero in the case of current limitation of load current
6 & 7	OUT (Load, L)	Output, protected high-side power output to the load. Both output pins have to be connected in parallel for operation according this spec (e.g. k _{ILIS}). Design the wiring for the max. short circuit current

Maximum Ratings at $T_j = 25$ °C unless otherwise specified

Parameter	Symbol	Values	Unit
Supply voltage (overvoltage protection see page 4)	$V_{ m bb}$	43	V
Supply voltage for full short circuit protection Tj Start=-40+150°C	$V_{ m bb}$	34	V
Load dump protection ¹⁾ $V_{LoadDump} = V_A + V_S$, $V_A = 13.5V$ $R_1^{(2)} = 2 \Omega$, $R_L = 1 \Omega$, $t_d = 200$ ms, $I_N = I_S$ low or high	V _{Load dump} ³⁾	60	V
Load current (Short circuit current, see page 5)	/ ∟	self-limited	Α
Operating temperature range Storage temperature range	T _j T _{stg}	-40+150 -55+150	ç
Power dissipation (DC), T _C ≤ 25 °C	P _{tot}	85	W
Inductive load switch-off energy dissipation, single pulse V_{bb} = 12V, $T_{J,start}$ = 150°C, T_{C} = 150°C const. I_{L} = 12.6 A, Z_{L} = 4,2 mH, 0 Ω : I_{L} = 4 A, Z_{L} = 330 mH, 0 Ω :	E _{AS} E _{AS}	0,41 3,5	J
Electrostatic discharge capability (ESD) IN: (Human Body Model) ST, IS: out to all other pins shorted: acc. MIL-STD883D, method 3015.7 and ESD assn. std. S5.1-1993 R=1.5k Ω ; C=100pF	V _{ESD}	1.0 4.0 8.0	kV
Input voltage (DC)	V _{IN}	-10 +16	V
Current through input pin (DC) Current through status pin (DC) Current through current sense pin (DC) see internal circuit diagrams page 8	I _{IN} I _{ST} I _{IS}	±2.0 ±5.0 ±14	mA

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¹⁾ Supply voltages higher than $V_{bb(AZ)}$ require an external current limit for the GND and status pins (a 150 Ω resistor in the GND connection is recommended).

²⁾ $R_{\rm I}$ = internal resistance of the load dump test pulse generator

 $^{^{3)}}$ $V_{Load\ dump}$ is setup without the DUT connected to the generator according to ISO 7637-1 and DIN 40839



Thermal Characteristics

Parameter and Conditions		Symbol	Values			Unit
			min	typ	max	
Thermal resistance	chip - case:	R_{thJC}			1.47	K/W
junction - ambient (free air):		R_{thJA}		-	75	
SMD version,			33			

Electrical Characteristics

Parameter and Conditions	Symbol	ol Values			Unit
at $T_j = 25$ °C, $V_{bb} = 12$ V unless otherwise specified		min	typ	max	

Load Switching Capabilities and Characteristics

R _{ON}	1	27 54	30 60	mΩ
$V_{ON(NL)}$		50		mV
I _{L(ISO)}	11.4	12.6		А
I _{L(NOM)}	4.0	4.5		А
I _{L(GNDhigh)}			8	mA
$t_{ m on} \ t_{ m off}$	25 25	70 80	150 200	μs
dV/dt _{on}	0.1		1	V/µs
-d V/dt _{off}	0.1		1	V/µs
	$V_{ m ON(NL)}$ $I_{ m L(ISO)}$ $I_{ m L(NOM)}$ $I_{ m L(GNDhigh)}$ $t_{ m on}$ $t_{ m off}$	$V_{\rm ON(NL)}$ $I_{\rm L(ISO)}$ 11.4 $I_{\rm L(NOM)}$ 4.0 $I_{\rm L(GNDhigh)}$ $t_{\rm on}$ 25 $t_{\rm off}$ 25 $dV/dt_{\rm on}$ 0.1	Image: Control of the control of th	Image: Control of the control of th

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⁴⁾ Device on 50mm*50mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 μ m thick) copper area for V_{bb} connection. PCB is vertical without blown air.



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Parameter and Conditions		Symbol	Values			Unit
at $T_j = 25$ °C, $V_{bb} = 12$ V unless otherwise specified			min	typ	max	
Operating Parameters						
Operating voltage 5)	<i>T</i> _j =-40+150°C:	$V_{\rm bb(on)}$	5.0		34	V
Undervoltage shutdown	Tj =-40+150°C:	V _{bb(under)}	3.2		5.0	V
Undervoltage restart	Tj =-40+25°C: Tj =+150°C:	V _{bb(u rst)}		4.5	5.5 6.0	V
Undervoltage restart of chargesee diagram page 13	le pump $T_j = -40+25$ °C: $T_j = 25150$ °C:	$V_{ m bb(ucp)}$		4.7	6.5 7.0	V
Undervoltage hysteresis Δ Vbb(under) = Vbb(u rst) - Vbb(under)	der)	$\Delta V_{ m bb(under)}$		0.5		V
Overvoltage shutdown	<i>T</i> _j =-40+150°C:	V _{bb(over)}	34		43	V
Overvoltage restart	Tj =-40+150°C:	V _{bb(o rst)}	33			V
Overvoltage hysteresis	<i>T</i> j =-40+150°C:	$\Delta V_{\text{bb(over)}}$		1		V
Overvoltage protection ⁶⁾ /bb=40 mA	<i>T</i> j =-40°C: <i>T</i> j =+25+150°C	$V_{\mathrm{bb}(AZ)}$	41 43	 47	 52	V
Standby current (pin 4) VIN=0	T _j =-40+25°C: T _j = 150°C:	I _{bb(off)}		4 12	15 25	μΑ
Off state output current (inclu	ded in I _{bb(off)}) T _J =-40+150°C:	I _{L(off)}			10	μΑ
Operating current (Pin 2) ⁷⁾ , VIN	µ=5 V	I _{GND}		1.2	3	mA

⁵⁾ At supply voltage increase up to V_{bb} = 4.7 V typ without charge pump, $V_{OUT} \approx V_{bb}$ - 2 V

Supply voltages higher than $V_{bb(AZ)}$ require an external current limit for the GND and status pins (a 150 Ω resistor in the GND connection is recommended). See also $V_{ON(CL)}$ in table of protection functions and circuit diagram page 9.

⁷⁾ Add I_{ST} , if $I_{ST} > 0$, add I_{IN} , if $V_{IN} > 5.5 \text{ V}$



Parameter and Conditions	Symbol		Values	;	Unit
at $T_j = 25$ °C, $V_{bb} = 12$ V unless otherwise specified		min	typ	max	
Protection Functions ⁸⁾		•	•		
Initial peak short circuit current limit (pin 4 to 6&7)	I _{L(SCp)}				
Τ _j =-40°C: Τ _j =25°C: Τ _j =+150°C:		48 40 31	56 50 37	65 58 45	Α
Repetitive short circuit shutdown current limit	I _{L(SCr)}				
$T_j = T_{jt}$ (see timing diagrams, page 12)			24		Α
Output clamp (inductive load switch off) at $V_{OUT} = V_{bb} - V_{ON(CL)}$; $I_{L} = 40 \text{ mA}$, $T_{j} = -40 ^{\circ}\text{C}$: $T_{j} = +25+150 ^{\circ}\text{C}$:	V _{ON(CL)}	41 43	 47	 52	V
Thermal overload trip temperature	$T_{\rm jt}$	150			°C
Thermal hysteresis	$\Delta T_{\rm jt}$		10		K
Reverse battery (pin 4 to 2) 9)	- V _{bb}			32	V
Reverse battery voltage drop (Vout > Vbb) /L = -5 A /j=150 °C:	-V _{ON(rev)}		600		mV
Diagnostic Characteristics					
Current sense ratio ¹⁰⁾ , static on-condition,					
$V_{IS} = 05 \text{ V}, V_{bb(on)} = 6.5^{11}27 \text{V},$					
$k_{\text{ILIS}} = I_{\text{L}} / I_{\text{IS}}$ $T_{\text{j}} = -40^{\circ}\text{C}, I_{\text{L}} = 5 \text{ A}$:	<i>k</i> _{ILIS}	4550	5000	6000	
$T_{\rm j}$ = -40°C, $I_{\rm L}$ = 0.5 A:		3300	5000	8000	
$T_{\rm j}=25+150^{\circ}\text{C},\ I_{\rm L}=5\text{ A:}$, $T_{\rm j}=25+150^{\circ}\text{C},\ I_{\rm L}=0.5\text{ A:}$		4550 4000	5000 5000	5550 6500	
Current sense output voltage limitation					
$T_{j} = -40 \dots + 150$ °C $I_{ S } = 0, I_{ L } = 5 \text{ A}$:	$V_{\rm IS(lim)}$	5.4	6.1	6.9	V
Current sense leakage/offset current $T_1 = -40 \dots + 150$ °C $V_1 N_1 = 0, V_1 S_1 = 0, I_2 = 0$,	0		1	^
$V_{\text{IN}=5} \text{ V, } V_{\text{IS}} = 0, I_{\text{L}} = 0$:	I _{IS(LL)}	0	 	1 15	μΑ
$V_{IN}=5$ V, $V_{IS}=0$, $I_{L}=0$. $V_{IN}=5$ V, $V_{IS}=0$, $V_{OUT}=0$ (short circuit):	I _{IS(LH)} I _{IS(SH)} 12)	0		10	

Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.

⁹⁾ Requires 150 Ω resistor in GND connection. The reverse load current through the intrinsic drain-source diode has to be limited by the connected load. Note that the power dissipation is higher compared to normal operating conditions due to the voltage drop across the intrinsic drain-source diode. The temperature protection is not active during reverse current operation! Input and Status currents have to be limited (see max. ratings page 2 and circuit page 9).

This range for the current sense ratio refers to all devices. The accuracy of the k_{ILIS} can be raised at least by a factor of two by matching the value of k_{ILIS} for every single device.

In the case of current limitation the sense current l_{IS} is zero and the diagnostic feedback potential V_{ST} is High. See figure 2b, page 11.

¹¹⁾ Valid if $V_{\rm bb(u\ rst)}$ was exceeded before.

¹²⁾ not subject to production test, specified by design



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Parameter and Conditions	Symbol	Values			Unit
at $T_j = 25$ °C, $V_{bb} = 12$ V unless otherwise specified		min	typ	max	·
Current sense settling time to $I_{\text{IS static}}\pm 10\%$ after positive input slope ¹³⁾ , $I_{\text{L}}=0$ 5 A, $T_{\text{j=}}-40+150^{\circ}\text{C}$	$t_{son(IS)}$			300	μs
Current sense settling time to 10% of $I_{\rm IS}$ static after negative input slope ¹³⁾ , $I_{\rm L} = 5$ 0 A, $T_{\rm j=-40+150^{\circ}C}$	$t_{ m soff(IS)}$		30	100	μs
Current sense rise time (60% to 90%) after change of load current ¹³⁾ , $I_L = 2.5$ 5 A	$t_{ m slc(IS)}$		10		μs
Open load detection voltage ¹⁴) (off-condition) <i>T</i> _j =-40150°C:	V _{OUT(OL)}	2	3	4	V
Internal output pull down (pin 6 to 2), VOUT=5 V, Tj=-40150°C	Ro	5	15	40	kΩ
Input and Status Feedback ¹⁵⁾					
Input resistance see circuit page 8	R_{I}	3,0	4,5	7,0	kΩ
Input turn-on threshold voltage $T_j = -40+150$ °C:	$V_{IN(T+)}$			3.5	V
Input turn-off threshold voltage $T_j = -40+150$ °C:	$V_{IN(T-)}$	1.5			V
Input threshold hysteresis	$\Delta V_{\rm IN(T)}$		0.5		V
Off state input current (pin 3), $V_{IN} = 0.4 \text{ V}$ $T_{j} = -40+150^{\circ}\text{C}$	I _{IN(off)}	1		50	μΑ
On state input current (pin 3), $V_{IN} = 5 \text{ V}$ $T_j = -40+150$ °C	I _{IN(on)}	20	50	90	μΑ
Delay time for status with open load after Input neg. slope (see diagram page 13)	t _{d(ST OL3)}		400		μs
Status delay after positive input slope ¹³⁾ T _j =-40 +150°C:	$t_{ m don(ST)}$		13		μs
Status delay after negative input slope ¹³⁾ T_{j} =-40 +150°C:	$t_{doff(ST)}$		1		μs
Status output (open drain)					
Zener limit voltage $T_j = -40 + 150$ °C, $I_{ST} = +1.6$ mA:	$V_{\rm ST(high)}$	5.4	6.1	6.9	V
ST low voltage $T_j = -40 + 25$ °C, $I_{ST} = +1.6$ mA: $T_j = +150$ °C, $I_{ST} = +1.6$ mA:	V _{ST(low)}			0.4 0.7	
Status leakage current, $V_{ST} = 5 \text{ V}$, $T_j = 25 \dots +150 ^{\circ}\text{C}$:	I _{ST(high)}			2	μΑ

¹³⁾ not subject to production test, specified by design

¹⁴⁾ External pull up resistor required for open load detection in off state.

 $^{^{\}rm 15)}\,$ If a ground resistor $R_{\rm GND}$ is used, add the voltage drop across this resistor.



Truth Table

	Input	Output	Status	Current Sense
	level	level	level	l _{IS}
Normal	L	L	Н	0
operation	Н	Н	L	nominal
Current-	L	L	Н	0
limitation	Н	Н	Н	0
Short circuit to	L	L	Н	0
GND	Н	L ¹⁶)	Н	0
Over-	L	L	Н	0
temperature	Н	L	Н	0
Short circuit to	L	Н	L ¹⁷)	0
V_{bb}	Н	Н	L	<nominal <sup="">18)</nominal>
Open load	L	L ¹⁹)	H (L ²⁰⁾)	0
	Н	Н	`L ´	0
Undervoltage	L	L	Н	0
	Н	L	L	0
Overvoltage	L	L	Н	0
	Н	L	L	0
Negative output voltage clamp	L	L	Н	0

L = "Low" Level H = "High" Level X = don't care

Z = high impedance, potential depends on external circuit Status signal after the time delay shown in the diagrams (see fig 5. page 12...13)

¹⁶⁾ The voltage drop over the power transistor is $V_{\rm bb}$ - $V_{\rm OUT}$ >typ.3V. Under this condition the sense current $I_{\rm IS}$ is

¹⁷⁾ An external short of output to V_{bb}, in the off state, causes an internal current from output to ground. If R_{GND} is used, an offset voltage at the GND and ST pins will occur and the $V_{\text{ST low}}$ signal may be errorious.

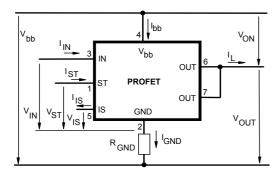
Low ohmic short to $V_{\rm bb}$ may reduce the output current $I_{\rm L}$ and therefore also the sense current $I_{\rm IS}$.

¹⁹⁾ Power Transistor off, high impedance

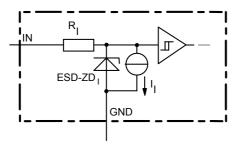
with external resistor between pin 4 and pin 6&7



Terms

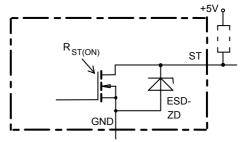


Input circuit (ESD protection)



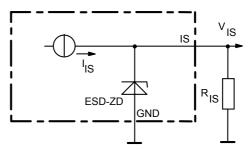
The use of ESD zener diodes as voltage clamp at DC conditions is not recommended.

Status output



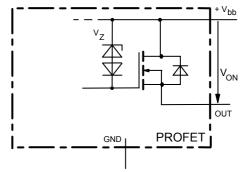
ESD-Zener diode: 6.1 V typ., max 5 mA; RST(ON) < 440 Ω at 1.6 mA, The use of ESD zener diodes as voltage clamp at DC conditions is not recommended.

Current sense output



ESD-Zener diode: 6.1 V typ., max 14 mA; $R_{IS} = 1 \text{ k}\Omega \text{ nominal}$

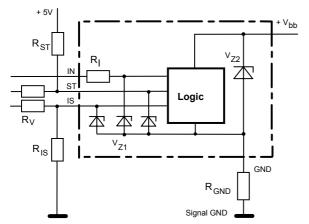
Inductive and overvoltage output clamp



Von clamped to 47 V typ.

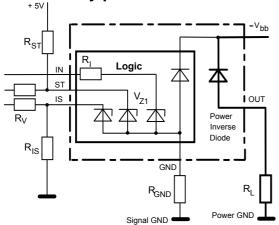


Overvoltage protection of logic part



 V_{Z1} = 6.1 V typ., V_{Z2} = 47 V typ., R_{I} = 4 k Ω typ, R_{GND} = 150 Ω , R_{ST} = 15 k Ω , R_{IS} = 1 k Ω , R_{V} = 15 k Ω ,

Reverse battery protection

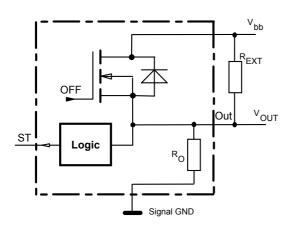


The load R_L is inverse on, temperature protection is not active

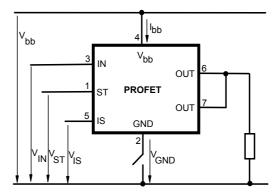
 R_{GND} = 150 Ω , R_{I} = 4 k Ω typ, R_{ST} \geq 500 Ω , R_{IS} \geq 200 Ω , R_{V} \geq 500 Ω ,

Open-load detection

OFF-state diagnostic condition: $V_{OUT} > 3 \text{ V typ.}$; IN low

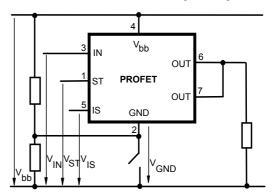


GND disconnect



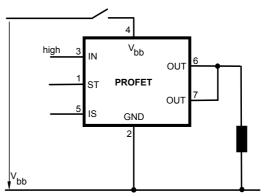
Any kind of load. In case of Input=high is $V_{OUT} \approx V_{IN}$ - $V_{IN(T+)}$. Due to V_{GND} >0, no V_{ST} = low signal available.

GND disconnect with GND pull up



Any kind of load. If $V_{GND} > V_{IN}$ - $V_{IN(T+)}$ device stays off Due to $V_{GND} > 0$, no $V_{ST} =$ low signal available.

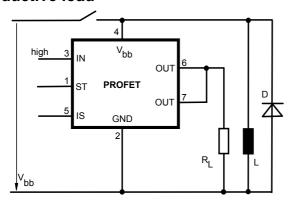
V_{bb} disconnect with energized inductive load



Normal load current can be handled by the PROFET itself.

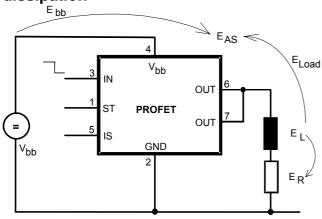


V_{bb} disconnect with charged external inductive load



If other external inductive loads L are connected to the PROFET, additional elements like D are necessary.

Inductive Load switch-off energy dissipation



Energy stored in load inductance:

$$E_{\rm L} = \frac{1}{2} \cdot {\rm L} \cdot {\rm I}_{\rm L}^2$$

While demagnetizing load inductance, the energy dissipated in PROFET is

$$E_{AS} = E_{bb} + E_L - E_R = V_{ON(CL)} \cdot i_L(t) dt$$

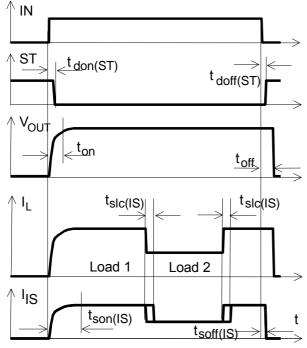
with an approximate solution for $R_L > 0 \Omega$:

$$E_{AS} = \frac{I_{L} \cdot L}{2 \cdot R_{L}} \cdot \left(V_{bb} + |V_{OUT(CL)}| \right) \cdot \ln \left(1 + \frac{I_{L} \cdot R_{L}}{|V_{OUT(CL)}|} \right)$$



Timing diagrams

Figure 1a: Switching a resistive load, change of load current in on-condition:



The sense signal is not valid during settling time after turn or change of load current.

Figure 1b: V_{bb} turn on:

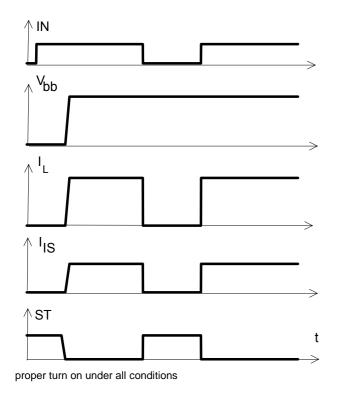


Figure 2a: Switching a lamp

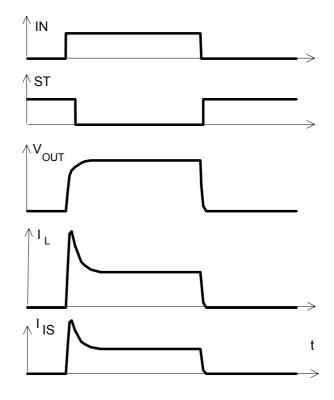


Figure 2b: Switching a lamp with current limit:

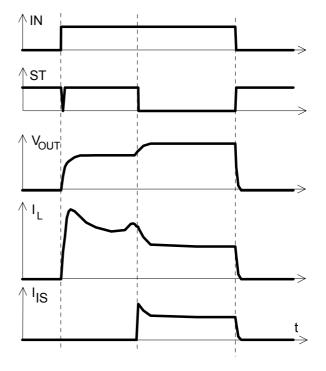
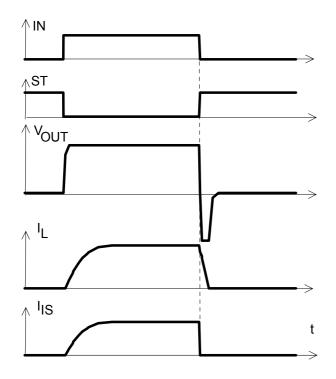




Figure 2c: Switching an inductive load:

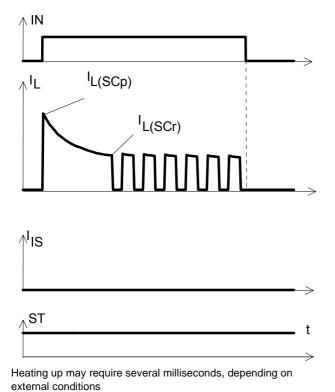
Figure 4a: Overtemperature: Reset if $T_j < T_{jt}$

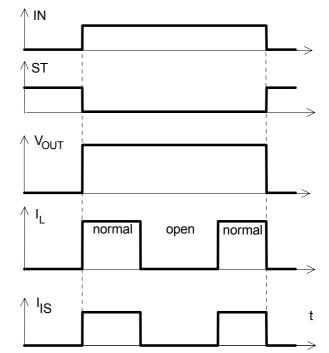


ST ST TIS T

Figure 3a: Short circuit: shut down by overtempertature, reset by cooling

Figure 5a: Open load: detection in ON-state, open load occurs in on-state





 $I_{L(SCp)}$ = 50 A typ. increases with decreasing temperature.



Figure 5b: Open load: detection in ON- and OFF-state (with REXT), turn on/off to open load

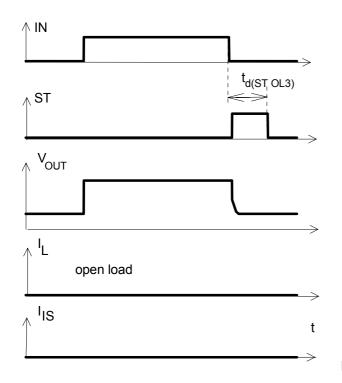


Figure 6b: Undervoltage restart of charge pump

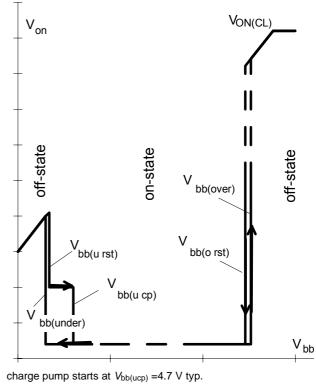
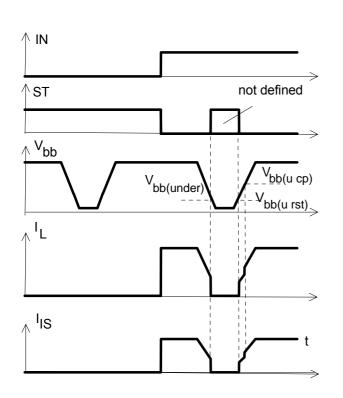


Figure 7a: Overvoltage:

Figure 6a: Undervoltage:



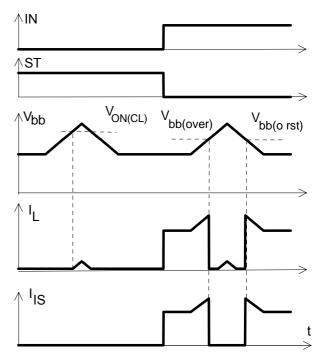




Figure 8a: Current sense versus load current:

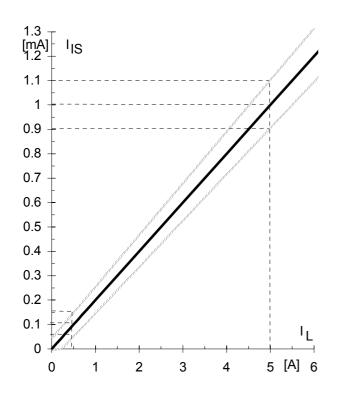


Figure 8b: Current sense ratio²¹:

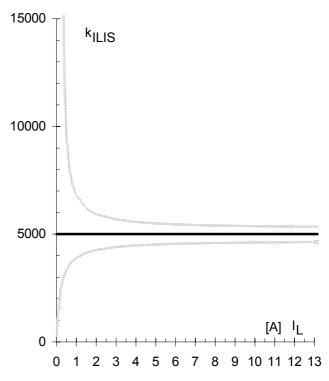
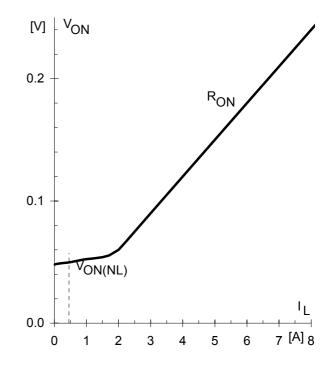


Figure 9a: Output voltage drop versus load current:



This range for the current sense ratio refers to all devices. The accuracy of the $k_{\rm ILIS}$ can be raised at least by a factor of two by matching the value of $k_{\rm ILIS}$ for every single device.

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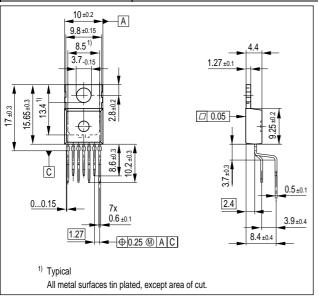


Package and Ordering Code

All dimensions in mm

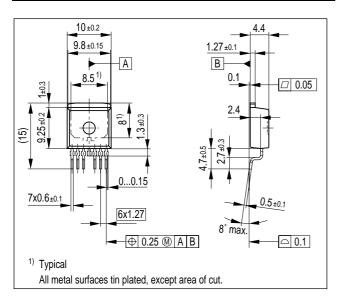
Standard (=staggered): P-TO220-7-11

	•
Sales code	BTS640S2
Ordering code	Q67060-S6307-A5



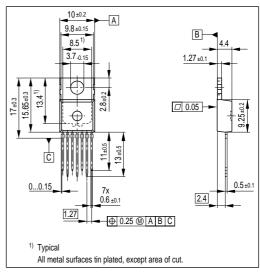
SMD: P-TO263-7-2 (tape&reel)

Sales code	BTS640S2 G
Ordering code	Q67060-S6307-A6



Straight: P-TO220-7-12

Sales Code	BTS640S2 S
Ordering code	Q67060-S6307-A7



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